Wi-Fi® + Bluetooth®

New!

	Description	Temperature Rating	Host Processor Requirements	Hardware Interfaces	Size	Certified Antenna Options
Sterling-LWB™	2.4 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.1	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART (Bluetooth®)	SiP: 10 mm x 10 mm x 1.2 mm Chip antenna or U.FL: 15.5 mm x 21 mm x 2 mm	• Chip Antenna • Dipole via U.FL • FlexPIFA via U.FL • FlexNotch via U.FL
TiWi-BLE™	2.4 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.0 and ANT+	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART, and Advanced Audio Interface (Bluetooth®)	13 mm x 18 mm x 1.9 mm	• Off-module chip • Dipole via U.FL • PIFA via U.FL • Flexible Dipole via U.FL
TiWi5™	2.4 & 5.8 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.0 and ANT+	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART, and Advanced Audio Interface (Bluetooth®)	13 mm x 18 mm x 1.9 mm	• Off-module SMT antenna • Dipole via U.FL

Module Certifications:

RCM Certification not available on TiWi-BLE or TiWi5.
All certifications pending for Sterling-LWB.

Wi-Fi®

New!

	Description	Temperature Rating	Host Processor Requriements	Hardware Interfaces	Size	Certified Antenna Options
TiWi-C-W™	2.4 GHz Stand-alone 802.11 b/g/n Wi-Fi module with ARM Cortex-M3 processor	-40° to +85°C	Development Architecture: Integration directly onto Cortex-M3 processor, or simple integration over UART interface to external MCUs or MPUs	UART	10.5 mm x 10.5 mm x 1.35 mm	• Off-module chip • Dipole via U.FL • Waterproof Dipole via U.FL • FlexPIFA™ via U.FL

IP

Accelerate your Socket-Based Wi-Fi Implementation

Serial-to-WiFi API

TiWi-C-W features a cloud agent for the TiWiConnect™ Module | Cloud | App cloud-connectivity platform

Module Certifications:

Bluetooth®

New!

	Description	Temperature Rating	Host Processor Requirements	Hardware Interfaces	Size	Certified Antenna Options
SaBLE-x™	2.4 GHz Built in CC2640 single-chip BLE 4.1 with ARM Cortex-M3 processor	-40° to +85°C	Integrated Cortex-M3 can act as MCU or network processor interface for applica-tions running on an external MCU	UART, SPI, I²C, Digital I/O, and Analog Inputs	11.6 mm x 17.9 mm x 2.3 mm	• PCB trace antenna • Dipole via U.FL • FlexPIFA™ via U.FL • FlexNotch™ via U.FL
TiWi-uB1™	2.4 GHz Built in CC2541 single-chip BLE 4.0 with 8051 MCU	-40° to +85°C	Integrated 8051 can act as MCU or network processor interface for applications running on an external MCU	UART, SPI, Digital I/O, and Analog Inputs	11.6 mm x 17.9 mm x 2.3 mm	• PCB trace antenna • Dipole via U.FL
TiWi-uB2™	2.4 GHz Bluetooth 2.1+ EDR, and BLE 4.0 module	-30° to +85°C	MCU or MPU with a serial port (UART)	HCI, UART, and Audio PCM interfaces	7 mm x 7 mm x 1.5 mm	• Off-module chip • Dipole via U.FL

Featured for SaBLE-x development:

Serial-to-BLE API

Module Certifications:

RCM Certification not available on TiWi-uB1 or TiWi-uB2.

802.15.4

	Description	Temperature Rating	Output Power	Receive Sensitivity	Processor	Radio	Size	Certified Antenna Options
ProFLEX™	High performance 802.15.4 radios and microcontrollers	-40° to +85°C	100	-98 dBm	MSP430	CC2520	22.8 mm x 41.4 mm	• Inverted F • Dipole via U.FL
SiFLEX™	High performance 802.15.4 radios and microcontrollers	-40° to +85°C	250	-102 dBm	ATxMega256A3U	AT86RF212B	22.8 mm x 41.4 mm	• RF castellation • Wire • Dipole via U.FL • Helical

Leverage the Power and Simplicity of FLEXConnect™

- Delivers range extension without the complexities of a full mesh network
- Pre-loaded on both ProFLEX01 and SiFLEX02 modules

Module Certifications for ProFLEX:

Module Certifications for SiFLEX: